

PATENT ASSIGNMENT COVER SHEET

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| CONVEYING PARTY DATA | |
| Name | Execution Date |
| JIN-HONG AN | 07/29/2010 |
| JAE-SOON KIM | 07/29/2010 |
| RECEIVING PARTY DATA | |
| Name: | SAMSUNG SDI CO., LTD. |
| Street Address: | 150-20, GONGSE-RO, GIHEUNG-GU |
| City: | YONGIN-SI, GYEONGGI-DO |
| State/Country: | REPUBLIC OF KOREA |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 13592151 |
| CORRESPONDENCE DATA | |
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| SIGNATURE: | /Heungsoo Choi/ |
| DATE SIGNED: | 05/30/2014 |
| Total Attachments: 2 | |
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Application No.: Unknown
Filing Date: Herewith

Client Code: SDIYPL.235AUS
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ASSIGNMENT

WHEREAS, I, the undersigned, have invented certain new and useful improvements in a **ELECTRONIC CIRCUIT MODULE AND METHOD OF MAKING THE SAME**, the specification of which was executed on even date herewith.

AND WHEREAS, **Samsung SDI Co., Ltd.**, (hereinafter "ASSIGNEE"), with its principal place of business at **428-5, Gongse-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea**, desires to acquire the entire right, title, and interest in and to the said improvements with respect to the United States of America, its territories and possessions.

NOW, THEREFORE, in light of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventor, do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

Date: July 29, 2010

Signature: Jin-Hong An

Name: Jin-Hong An

Address: c/o Samsung SDI Co., Ltd.

428-5, Gongse-dong, Giheung-gu, Yongin-si,
Gyeonggi-do, Republic of Korea

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Date: July 29, 2010

Signature: Jae-Soon Kim

Name: Jae-Soon Kim
Address: c/o Samsung SDI Co., Ltd.

428-5, Gongse-dong, Giheung-gu, Yongin-si,
Gyeonggi-do, Republic of Korea

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